



| General Information | |
|---------------------|-------------------------------|
| Series | B45196P |
| Dielectric | MnO ₂ Tantalum |
| Style | SMD Chip |
| Description | SMD, Molded, High Temperature |
| Features | High Temperature, Automotive |
| RoHS | Yes |
| Termination | Tin |
| Qualifications | AEC-Q200 |
| AEC-Q200 | Yes |
| Notes | Obsolete. |

| Dimensions | |
|------------|----------------|
| Footprint | 7343 |
| L | 7.3mm +/-0.3mm |
| W | 4.3mm +/-0.3mm |
| H | 4.1mm +/-0.3mm |
| S | 1.3mm +/-0.3mm |
| F | 2.4mm +/-0.1mm |
| K | 1.8mm TYP |

| Specifications | |
|-----------------------|--|
| Capacitance | 33 uF |
| Capacitance Tolerance | 10% |
| Voltage DC | 35 VDC (85C), 27.89 VDC (125C), 23.45 VDC (150C) |
| Temperature Range | -55/+150°C |
| Rated Temperature | 85°C |
| Dissipation Factor | 6% |
| Failure Rate | N/A |
| Resistance | 0.5 Ohms (100kHz) |
| Ripple Current | 574.5 mAmps (25C), 517.1 mAmps (85C), 229.8 mAmps (125C) |
| Leakage Current | 11.6 uA |

| Packaging Specifications | |
|--------------------------|------------|
| Packaging | T&R, 330mm |
| Packaging Quantity | 4750 |